

N-channel 650 V, 0.012 Ω typ., 143 A MDmesh[™] M5 Power MOSFET in an ISOTOP package

Datasheet - production data



ISOTOP™

Figure 1: Internal schematic diagram



Features

Order code	V _{DS} @ T _{Jmax}	R _{DS(on)} max.	ID
STE145N65M5	710 V	0.015 Ω	143 A

- Extremely low R_{DS(on)}
- Low gate charge and input capacitance
- Excellent switching performance
- 100% avalanche tested

Applications

• Switching applications

Description

This device is an N-channel Power MOSFET based on the MDmesh[™] M5 innovative vertical process technology combined with the wellknown PowerMESH[™] horizontal layout. The resulting product offers extremely low onresistance, making it particularly suitable for applications requiring high power and superior efficiency.

Table 1: Device summary

Order code	Marking	Package	Packaging
STE145N65M5	145N65M5	ISOTOP	Tube

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This is information on a product in full production.

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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{GS}	Gate-source voltage	± 25	V
I _D	Drain current (continuous) at $T_C = 25 \ ^{\circ}C$	143	А
ID	Drain current (continuous) at T _C = 100 °C	90	Α
I _{DM} ⁽¹⁾	Drain current (pulsed)	572	Α
P _{TOT}	Total dissipation at $T_C = 25 \text{ °C}$	679	W
I _{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by Tj max)	12	А
E _{AS}	Single pulse avalanche energy (starting $T_j = 25$ °C, $I_D = I_{AR}$, $V_{DD} = 50$ V)	2420	mJ
dv/dt ⁽²⁾	Peak diode recovery voltage slope	15	V/ns
V _{ISO}	Isolation withstand voltage applied between each pin and heatsink plate (AC voltage, $t = 60 \text{ s}$)	2.5	kV
T _{stg}	Storage temperature	- 55 to 150	•
Tj	Max. operating junction temperature	150	

Notes:

 $\ensuremath{^{(1)}}\ensuremath{\mathsf{Pulse}}$ width limited by safe operating area.

 $\label{eq:linear} {}^{(2)}I_{SD} \leq 143 \text{ A}, \text{ di/dt} \leq 400 \text{ A/}\mu\text{s}; \text{ }V_{\text{DS}(\text{peak})} < \text{V}_{(\text{BR})\text{DSS}}, \text{ }V_{\text{DD}} = 400 \text{ V}.$

Table 3: Thermal data

Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case max	0.184	°C/W
R _{thj-amb}	Thermal resistance junction-ambient max	30	°C/W



2 Electrical characteristics

 $T_C = 25$ °C unless otherwise specified

Table 4: On/off states								
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit		
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS} = 0 V, I_D = 1 mA	650			V		
-	Zara gata valtaga drain gurrant	V _{GS} = 0 V, V _{DS} = 650 V			10	μA		
IDSS	Zero gate voltage drain current	V _{GS} = 0 V, V _{DS} = 650 V, T _C = 125 °C			100	μA		
I _{GSS}	Gate-body leakage current	V _{DS} = 0 V, V _{GS} = ±25 V			±100	nA		
V _{GS(th)}	Gate threshold voltage	$V_{\text{DS}} = V_{\text{GS}}, \ I_{\text{D}} = 250 \ \mu\text{A}$	3	4	5	V		
R _{DS(on)}	Static drain-source on-resistance	V_{GS} = 10 V, I_{D} = 69 A		0.012	0.015	Ω		

Table 5: Dynamic								
Symbol	Parameter	er Test conditions		Тур.	Max.	Unit		
C _{iss}	Input capacitance		-	18500	-	pF		
Coss	Output capacitance	V_{DS} = 100 V, f = 1 MHz, V_{CS} = 0 V	-	413	-	pF		
Crss	Reverse transfer capacitance	163 - 0 1	-	11	-	pF		
C _{o(er)} ⁽¹⁾	Equivalent output capacitance energy related		-	415	-	pF		
C _{o(tr)} ⁽²⁾	Equivalent output capacitance time related	$v_{GS} = 0, v_{DS} = 0.00520$ v	-	1950	-	pF		
R _G	Intrinsic gate resistance	f = 1 MHz, open drain	-	0.7	-	Ω		
Qg	Total gate charge	$V_{DD} = 520 \text{ V}, \text{ I}_{D} = 69 \text{ A},$	-	414	-	nC		
Q _{gs}	Gate-source charge	V _{GS} = 10 V (see Figure 15: "Test circuit for gate	-	114	-	nC		
Q _{gd}	Gate-drain charge	charge behavior")	-	164	-	nC		

Notes:

 $^{(1)}C_{o(er)}$ is defined as a constant equivalent capacitance giving the same stored energy as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}

 $^{(2)}C_{o(tr)}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}



Electrical characteristics

Table 6: Switching times						
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(V)}	Voltage delay time	$V_{DD} = 400 \text{ V}, \text{ I}_{D} = 85 \text{ A}$	-	255	-	ns
t _{r(V)}	Voltage rise time	$R_G = 4.7 \Omega$, $V_{GS} = 10 V$	-	11	-	ns
t _{f(i)}	Current fall time	inductive load switching and	-	82	-	ns
t _{C(off)}	Crossing time	diode recovery times" and Figure 19: "Switching time waveform")	-	88	-	ns

Table 7. Source drain diode	Table 7	7:	Source	drain	diode
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Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current		-		143	А
I _{SDM} , ⁽¹⁾	Source-drain current (pulsed)		-		572	А
V _{SD} ⁽²⁾	Forward on voltage	$V_{GS} = 0 V, I_{SD} = 143 A$	-		1.5	V
t _{rr}	Reverse recovery time	I _{SD} = 143 A, di/dt = 100 A/µs,		568		ns
Qrr	Reverse recovery charge	V _{DD} = 100 V (see Figure 16: "Test circuit for inductive load	-	14.5		μC
I _{RRM}	Reverse recovery current	switching and diode recovery times")	-	51		А
t _{rr}	Reverse recovery time	I _{SD} = 143 A, di/dt = 100 A/µs,	-	728		ns
Q _{rr}	Reverse recovery charge	$V_{DD} = 100 \text{ V}, \text{ T}_{j} = 150 \text{ °C}$ (see Figure 16: "Test circuit for	-	24.5		μC
I _{RRM}	Reverse recovery current	inductive load switching and diode recovery times")	-	67		A

Notes:

 $^{(1)}\mbox{Pulse}$ width is limited by safe operating area

⁽²⁾Pulsed: pulse duration = 300 μ s, duty cycle 1.5%



2.2









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Electrical characteristics







The previous figure E_{on} includes reverse recovery of a SiC diode.

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3 Test circuits







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4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.



4.1 **ISOTOP** package information





Package information

Table 8: ISOTOP mechanical data					
mm					
Dim.	Min.	Тур.	Max.		
A	11.80		12.20		
A1	8.90		9.10		
В	7.80		8.20		
С	0.75		0.85		
C2	1.95		2.05		
D	37.80		38.20		
D1	31.50		31.70		
E	25.15		25.50		
E1	23.85		24.15		
E2		24.80			
G	14.90		15.10		
G1	12.60		12.80		
G2	3.50		4.30		
F	4.10		4.30		
F1	4.60		5		
ØP	4		4.30		
P1	4		4.40		
S	30.10		30.30		



5 **Revision history**

Date	Revision	Changes
18-Nov-2013	1	First release.
12-Nov-2015 2 Updated title, features a Document status promo Modified: Table 2: "Absorbance stored energy Minor text changes.		Updated title, features and description on cover page. Document status promoted from preliminary to production data. Modified: <i>Table 2: "Absolute maximum ratings"</i> and <i>Figure 12: "Output capacitance stored energy"</i> Minor text changes.



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25.330.1653.	1 25.330.4753.1	25.330.5253.1	25.334.3253.1	25.334.3353.1	25.350.2053.0	25.352.4753.1	25.522.3253.0	<u>T483C</u> <u>T484C</u>
<u>T485F</u> <u>T485</u>	H T512F-YEB	T513F T514F	<u>T554</u> <u>T612FSE</u>	25.161.3453.0	25.179.2253.0	25.194.3253.0	25.325.1253.1	25.326.4253.1
25.330.0953.	1 25.332.4353.1	25.350.1653.0	25.350.2453.0	25.352.1453.0	25.352.1653.0	25.352.2453.0	25.352.5453.1	25.522.3353.0
25.602.4053.	0							